

Abstract

A lead frame and a method of fabrication thereof

Disclosed is a method of manufacturing a lead frame, which comprises the steps of:
providing an electrically-conductive base material having first and second planar sides;
5 forming a plurality of conductive contact points on the first planar side of the base material;
providing a non-conductive filling material over the first planar side of the base material so
that the filling material fills spaces in-between the plurality of contact points to a form a
layer comprising the filling material and the plurality of contact points; and etching the
second planar side of the base material to expose a pattern of the filling material from the
10 second planar side of the base material and to thereby form a plurality of isolated
conductive regions on the second planar side of the base material, each isolated
conductive region being connected with at least a respective one of the plurality of contact
points on the first planar side of the base material. A lead frame structure is also disclosed.

15 [FIG. 2c]